

ABSTRACT OF THE DISCLOSURE

A semiconductor package includes a first redistribution layer, a first semiconductor chip on the first redistribution layer, a molding layer covering the first semiconductor chip, metal pillars around the first semiconductor chip and connected to the first redistribution layer, a second redistribution layer on the molding layer and connected to the metal pillars, and a second semiconductor chip on the second redistribution layer. The metal pillars extend through the molding layer. When viewed in plan, the second semiconductor chip overlaps the first semiconductor chip and the metal pillars. A method of manufacturing the semiconductor package obtains a wafer map from a first substrate that includes a plurality of first semiconductor chips and uses the wafer map in selectively stacking second semiconductor chips on the first semiconductor chips.

FIG. 2